



Material Content Data Sheet



Sales Product Name				IPI100N08S2-07		Issued		25. September 2017	
MA#				MA000275853					
Package				PG-TO262-3-1		Weight*		1578.28 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.294	0.78	0.78	7789	7789	
leadframe	non noble metal	iron	7439-89-6	0.851	0.05		539		
	inorganic material	phosphorus	7723-14-0	0.255	0.02		162		
	non noble metal	copper	7440-50-8	849.682	53.84	53.91	538358	539059	
wire	non noble metal	aluminium	7429-90-5	7.583	0.48	0.48	4805	4805	
encapsulation	organic material	carbon black	1333-86-4	8.672	0.55		5495		
	plastics	epoxy resin	-	95.394	6.04		60442		
	inorganic material	silicondioxide	60676-86-0	474.080	30.04	36.63	300377	366314	
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9629	9629	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		145		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	538357	145	
solder	noble metal	silver	7440-22-4	0.192	0.01		122		
	non noble metal	tin	7440-31-5	0.154	0.01		98		
	non noble metal	lead	7439-92-1	7.350	0.47	0.49	4657	4877	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		67		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		20		
	non noble metal	copper	7440-50-8	106.210	6.73	6.74	67295	67382	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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